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Octal D-type Flip-Flops (with Clear)



ADE-205-482 (Z) 1st. Edition Sep. 2000

Description

This device contains 8 master-slave flip-flops with a common clock and common clear. Data on the D input having the specified setup and hold times is transferred to the Q output on the low to high transition of the clock input. The clear input when low, sets all outputs to a low state.

Features

- High Speed Operation: t_{pd} (Clock to Q) = 18 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Inputs		Outputs		
Clear	Clock	D	Q	
L	Х	Х	L	
Н		Н	Н	
Н		L	L	
Н	L	Х	No change	
Н		Х	No change	

Function Table

Pin Arrangement



Logic Diagram



DC Characteristics

			Ta =	: 25°C)	Ta = - +85°0	-40 to C			
ltem	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Condition	ns
Input voltage	V _{IH}	2.0	1.5			1.5	_	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—	_		
	VIL	2.0		_	0.5	—	0.5	V		
		4.5			1.35		1.35	_		
		6.0			1.8	_	1.8	_		
Output voltage	V _{OH}	2.0	1.9	2.0	_	1.9	—	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -20 \ \mu A$
		4.5	4.4	4.5	—	4.4	—	_		
		6.0	5.9	6.0	_	5.9	—	_		
		4.5	4.18		_	4.13	—	_		I _{он} = -4 mА
		6.0	5.68	_	—	5.63	—			I _{он} = -5.2 mА
	V _{OL}	2.0	_	0.0	0.1	_	0.1	V	$Vin = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 20 \ \mu A$
		4.5	_	0.0	0.1		0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5		_	0.26		0.33	_		$I_{OL} = 4 \text{ mA}$
		6.0		_	0.26		0.33	_		I _{oL} = 5.2 mA
Input current	lin	6.0			±0.1		±1.0	μΑ	Vin = V _{cc} or GN	ND
Quiescent supply current	I _{cc}	6.0	—		4.0	—	40	μA	Vin = V _{cc} or GN	ND, lout = $0 \mu A$

			Ta = 25°C		Ta = –40 to +85°C				
Item	Symbol	V _{cc} (V)	Min	Тур	Max	Min	Max	Unit	Test Conditions
Maximum clock	\mathbf{f}_{\max}	2.0	_	_	6	—	5	MHz	
frequency		4.5	_	_	30	_	24	_	
		6.0		_	35		28	_	
Propagation delay	t _{PHL}	2.0		_	145		180	ns	Clock to Q
time		4.5		18	29		36	_	
		6.0		_	25		31	_	
	t _{PLH}	2.0		_	145		180	ns	_
		4.5	_	18	29	_	36	_	
		6.0		_	25		31	_	
	t _{PHL}	2.0		_	145		180	ns	Clear to Q
		4.5		15	29	_	36	_	
		6.0		_	25	_	31	_	
Setup time	t _{su}	2.0	100	_	_	125	—	ns	Data to clock
		4.5	20	2		25	—	_	
		6.0	17	_	_	21	—	_	
Hold time	t _h	2.0	5	_		5	—	ns	Clock to data
		4.5	5	0		5	—	_	
		6.0	5			5	—	_	
Removal time	t _{rem}	2.0	100	_		125	—	ns	Clear to clock
		4.5	20	-1		25	_	_	
		6.0	17	_		21	_	_	
Pulse width	t _w	2.0	80	_		100	—	ns	Clock, clear
		4.5	16	8		20	_	_	
		6.0	14	_		17	_	_	
Output rise/fall	t _{TLH}	2.0		_	75		95	ns	
time	t_{THL}	4.5		5	15		19	-	
		6.0	_	_	13	—	16	-	
Input capacitance	Cin		—	5	10	—	10	pF	

AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Package Dimensions











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Hitachi, Ltd.

Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

	Hitachi Semiconductor America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Fel: <1> (408) 433-1990 Fax: <1>(408) 433-0223	Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 180-0 Fax: <49> (89) 9 29 30 00	Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel : <65>-538-6533/538-8577 Fax : <65>-538-6933/538-3877 URL : http://www.hitachi.com.sg	Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong
		Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 585160	Hitachi Asia Ltd. (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building, Taipei (105), Taiwan Tel : <886>-(2)-2718-3666 Fax : <886>-(2)-2718-3860 Telex : 23222 HAS-TP URL : http://www.hitachi.com.tw	Tel : <852>-(2)-735-9218 Fax : <852>-(2)-730-0281 URL : http://www.hitachi.com.hk

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